

Secondary Alloyed 1N Copper Wire for Bonding in Microelectronics Device

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ABSTRACT

A secondary alloyed 1N copper wire for bonding in microelectronics comprising one or more of a group of Ag, Ni, Pd, Au, Pt, and Cr as corrosion resistance alloying material, wherein a concentration of said corrosion resistance alloying material is
10 between about 0.09wt% and about 9.9wt%.

FIG. 1

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